(12) **United States Design Patent** (10) **Patent No.: US D517,384 S**
**Ishii et al.** (45) **Date of Patent: ** Mar. 21, 2006**

(54) **WIRE SOLDER APPLICATOR**

(75) Inventors: **Kou Ishii**, Tokyo (JP); **Yoshiaki Yanagawa**, Tokyo (JP)

(73) Assignees: **Pentel Kabushiki Kaisha**, Tokyo (JP); **Senju Metal Industry Co., Ltd.**, Tokyo (JP)

(**) Term: **14 Years**

(21) Appl. No.: **29/209,789**

(22) Filed: **Jul. 21, 2004**

(30) **Foreign Application Priority Data**

Jan. 22, 2004 (JP) ....................................... 2004-001394

(51) **LOC (8) Cl.** .................................................... **08-05**
(52) **U.S. Cl.** .......................................................... **D8/30**
(58) **Field of Classification Search** .................... D8/30; 219/229, 230, 227; 228/41, 52, 53
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

| | | | | |
|---|---|---|---|---|
| D266,980 S | * 11/1982 | Fortune | D8/14 |
| 4,793,541 A | * 12/1988 | Dravnieks | 228/52 |
| 5,031,817 A | * 7/1991 | Chen | 128/864 |
| 5,379,941 A | * 1/1995 | Partel | 228/33 |
| 5,782,394 A | * 7/1998 | Langley | 226/187 |
| 5,813,591 A | * 9/1998 | Quinn et al. | 228/41 |
| 6,369,359 B1 | * 4/2002 | Morrison | 219/229 |

* cited by examiner

*Primary Examiner*—Philip S. Hyder
(74) *Attorney, Agent, or Firm*—Adams & Wilks

(57) **CLAIM**

The ornamental design for a wire solder applicator, as shown and described.

**DESCRIPTION**

FIG. **1** is a perspective view of a wire solder applicator showing our new design;
FIG. **2** is a front view thereof;
FIG. **3** is a rear view thereof;
FIG. **4** is a bottom view thereof;
FIG. **5** is a left side view thereof; and,
FIG. **6** is a right side view thereof.

**1 Claim, 2 Drawing Sheets**

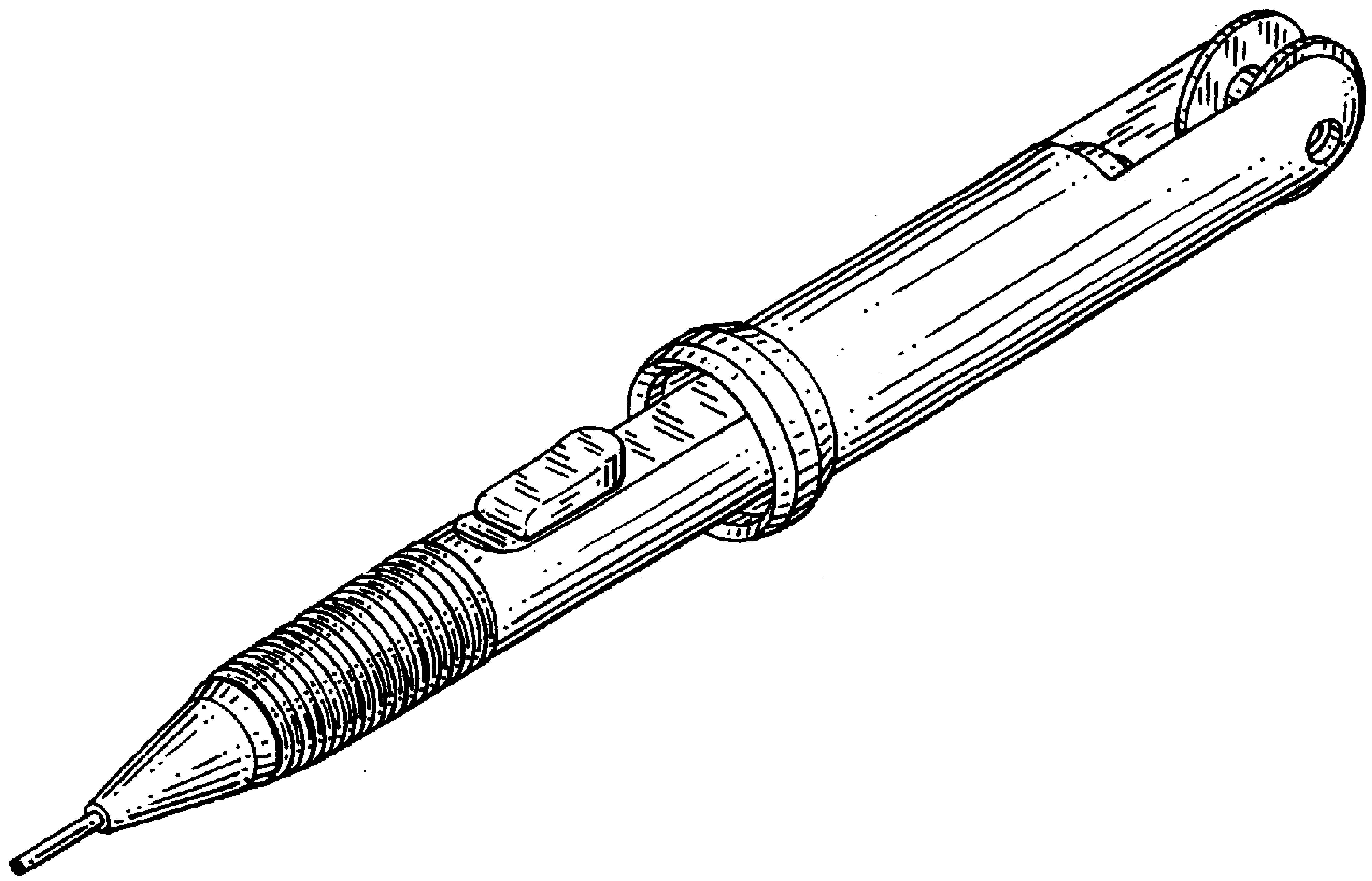

FIG. 1

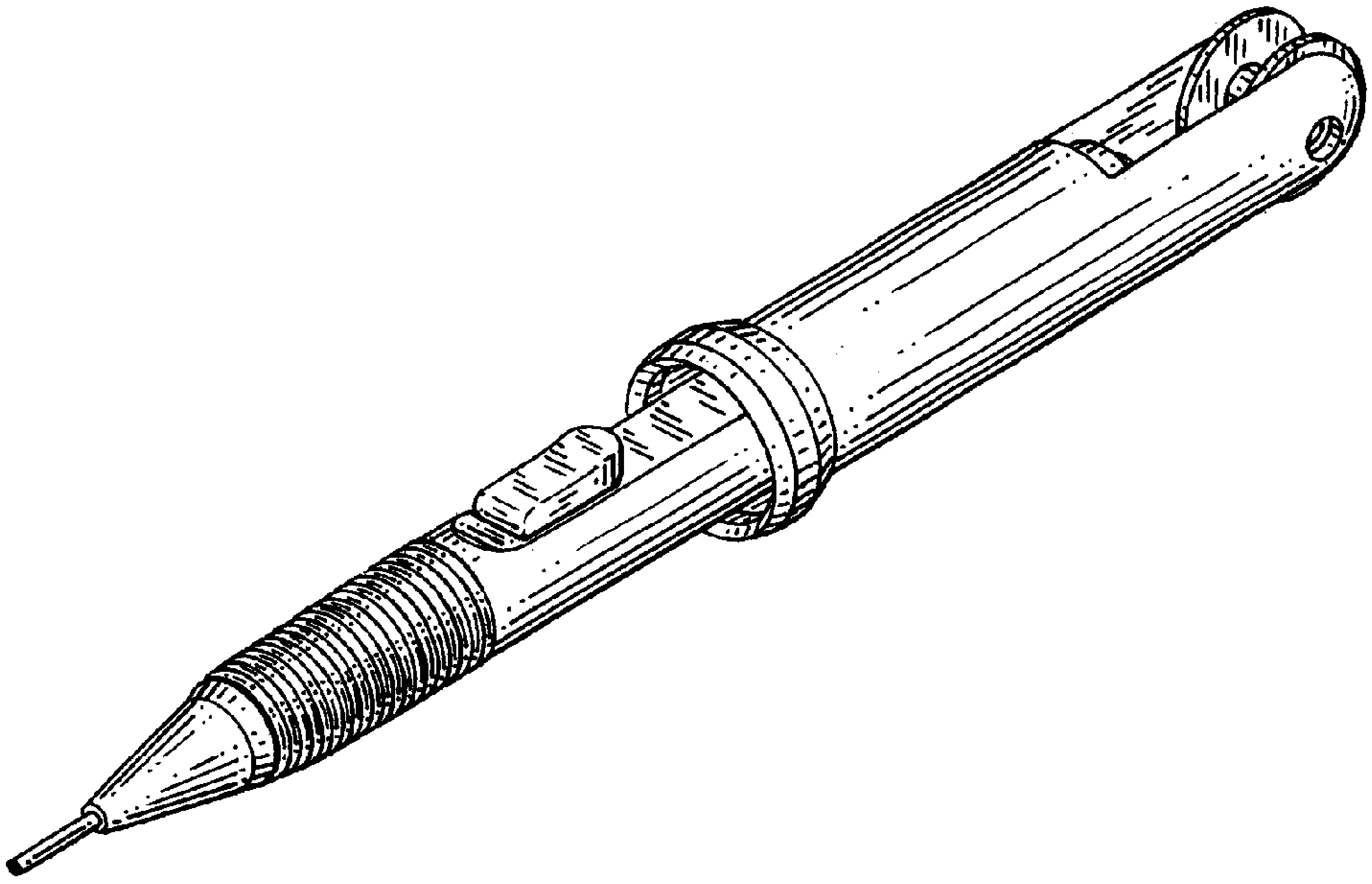

FIG. 2

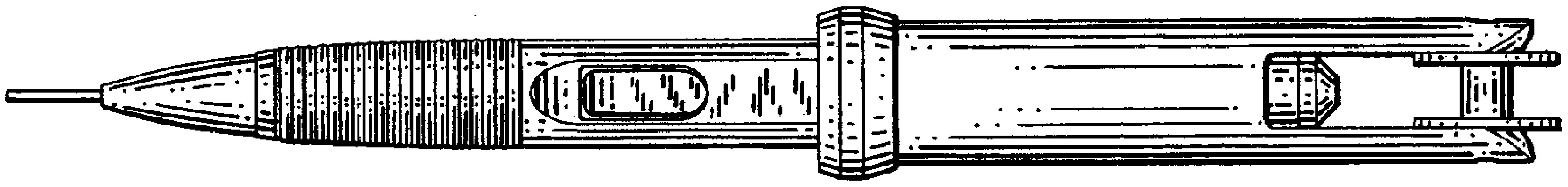

FIG. 3

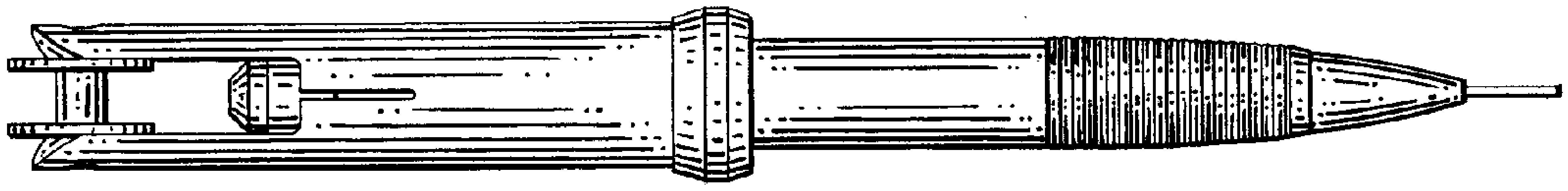

FIG. 4

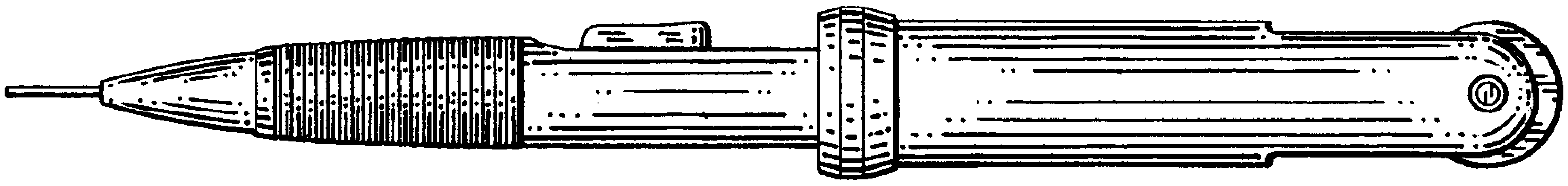

FIG. 5

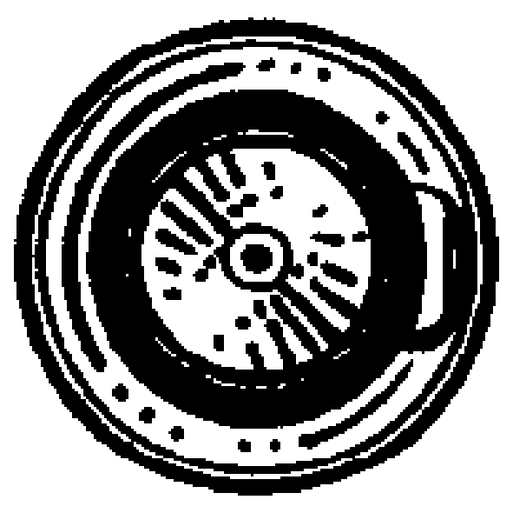

FIG. 6